

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3206158

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
WENG HONG TEH	12/04/2012
CHIA-PIN CHIU	12/03/2012
RECEIVING PARTY DATA	
Name:	INTEL CORPORATION
Street Address:	2200 MISSION COLLEGE BLVD.
City:	SANTA CLARA
State/Country:	CALIFORNIA
Postal Code:	95054
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13707159
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	612-373-6900
Email:	request@slwip.com
Correspondent Name:	SCHWEGMAN, LUNDBERG & WOESSNER/INTEL
Address Line 1:	PO BOX 2938
Address Line 4:	MINNEAPOLIS, MINNESOTA 55402
ATTORNEY DOCKET NUMBER:	884.M13US1
NAME OF SUBMITTER:	NANCY CUNDALL
SIGNATURE:	/Nancy Cundall/
DATE SIGNED:	01/30/2015
Total Attachments: 5	
source=884M13US1Assignment#page1.tif	
source=884M13US1Assignment#page2.tif	
source=884M13US1Assignment#page3.tif	
source=884M13US1Assignment#page4.tif	
source=884M13US1Assignment#page5.tif	

RECORDATION FORM COVER SHEET
PATENTS ONLY

Atty Ref/Docket No.: 884.M13US1

Patent and Trademark Office

To the Director of the U.S. Patent and Trademark Office: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Weng Hong Teh, Chia-Pin Chiu

Additional name(s) of conveying party(ies) attached?

☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment

☐ Merger

☐ Security Agreement ☐ Change of Name

☐ Other

Execution Date: December 4, 2012, December 3, 2012

2. Name and address of receiving party(ies):

Name: Intel Corporation

Street Address: 2200 Mission College Blvd.

City: Santa Clara State: CA Zip: 95054

Country: United States of America

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)

Serial No. 13/707,159

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Rigel J. Menard

Address:

Schwegman Lundberg & Woessner, P.A.

P.O. Box 2938

Minneapolis, MN 55402--0938

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$ 0.00

☐ Enclosed

☐ Authorized to be charged to deposit account
504238

8. Please charge any additional fees or credit any over payments to our Deposit Account No.: 504238

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Rigel J. Menard/Reg. No. 66,520

Name of Person Signing

/Rigel J Menard/ 01/27/2015

Signature

Date

Total number of pages including cover sheet: 5

Mail documents to be recorded with required cover sheet information to:

Commissioner of Patents and Trademarks

Mail Stop Assignment Recordation Services

P.O. Box 1450

Alexandria, VA 22313-1450

PATENT
REEL: 034855 FRAME: 0168

Attorney Docket No. 884.M13US1

Client Ref. No. P49052

ASSIGNMENT

WHEREAS, Weng Hong Teh and Chia-Pin Chiu (hereinafter the "Undersigned") have made one or more inventions and other subject matter (hereinafter collectively referred to as the "Invention") which are described in a patent application filed on December 6, 2012, which application was assigned US patent application serial number 13/707,159, and which is titled HIGH DENSITY SUBSTRATE ROUTING IN BBUL PACKAGE.

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency, and adequacy of which are hereby acknowledged by the Undersigned, the Undersigned do hereby irrevocably and unconditionally:

CONVEY, ASSIGN, AND TRANSFER to Intel Corporation (the "Assignee"), a corporation of the State of Delaware, having a place of business at 2200 Mission College Blvd., Santa Clara, CA 95054, the Undersigned's entire right, title, and interest for the United States and all foreign countries and jurisdictions in and to:

the invention which is disclosed in the above-identified application or applications;
such application or applications, and all divisional, continuing (including continuation-in-part), substitute, renewal, reissue, and all other applications for a patent or patents which have been or shall be filed in the United States (including all provisional and non-provisional applications), and in all foreign countries and jurisdictions based in whole or in part on any of such invention (including any application for a utility model or an innovation patent application);

all original and reissued patents which have been or shall be issued in the United States and all foreign countries and jurisdictions based in whole or in part on any of such invention;

including the right to claim priority to the above-identified patent application or applications in relation to subject matter based in whole or in part on the above-identified patent application or applications and any of the foregoing including the right to file foreign applications under the provisions of any convention or treaty;

and including the right to all causes of action, remedies, and other enforcement rights related to the above-identified application or applications, including without limitation the right to sue for past, present, or future infringement, misappropriation, or violation of any and all rights related to the above-identified patent application or applications and any of the foregoing, including the right to obtain and collect damages for past, present, or future infringement;

AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such invention to the Assignee;

AUTHORIZE AND REQUEST that any attorney associated with U.S. Patent and Trademark Office (USPTO) Customer No. 45457 may (directly or through his/her designee) delete, insert, or alter any information related to the above-identified patent application or applications or any of the foregoing, after execution of this Assignment;

Assignment

Assignors: Weng Hong Teh et al.

Title: HIGH DENSITY SUBSTRATE ROUTING IN BBUL PACKAGE

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Docket No: 884.M13US1

Client Ref. No. P49052

WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or shall be made to others by the Undersigned, and that the full right to convey the same as herein expressed is possessed by the Undersigned;

COVENANT, that when requested and without compensation, but at the expense of the Assignee, in order to carry out in good faith the intent and purpose of this Assignment, the Undersigned shall (1) execute all provisional, non-provisional, divisional, continuing (including continuation-in-part), substitute, renewal, reissue, and all other patent applications for the invention; (2) execute all rightful oaths, declarations, assignments, powers of attorney and other papers for the invention; (3) communicate to the Assignee all facts known to the Undersigned relating to the invention and the history thereof; (4) cooperate with the Assignee in any interference, reexamination, reissue, opposition, dispute, or litigation involving any of the applications or patents for the invention; and (5) take such further actions as the Assignee shall reasonably consider necessary or desirable for vesting title to such invention in the Assignee, or for securing, maintaining and enforcing proper patent protection for the invention;

COVENANT, that should any provision of this agreement be held unenforceable by an authority of competent jurisdiction, such a ruling shall not affect the validity and enforceability of the remaining provisions. To the extent that any such provision is found to be unenforceable, the Undersigned, when requested and without compensation shall act in good faith to substitute for such provision a new provision with content and purpose as close as possible to the provision deemed unenforceable.

THIS AGREEMENT IS TO BE BINDING on the heirs, assigns, representatives, and successors of the Undersigned, and is to extend to the benefit of the successors, assigns, and nominees of the Assignee.

AGREED as of the date of my signature below:

PATENT

REEL: 034855 FRAME: 0170

Assignment

Assignors: Weng Hong Teh et al.

Title: HIGH DENSITY SUBSTRATE ROUTING IN BBUL PACKAGE

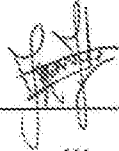
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Docket No: 884 M13081

Client Ref. No: P49052

Assignor:

(Signature):



Name: Weng Hong Teh

City/State: Phoenix, AZ

Date: 12/4/12

Assignment

Assignors: Wang, Hong-Tai et al.

Title: HIGH DENSITY SUBSTRATE ROUTING IN BULK PACKAGE

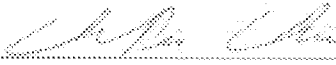
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DocId: 584 M1 R181

Client Ref. No. P49052

Assignor:

(Signature):



Name: Chia-Pin Chiu

City/State: Tempe, AZ

Date: 12-3-2012